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November 2012

# FSA801 — USB2.0 High-Speed (480 Mbps), UART, and Audio Switch with Negative Signal Capability

## **Features**

- 3:1 Switch Handles:
  - Audio Headsets
  - UART
  - Up to Two High- and Low-Speed USB Data
- USB Charger Detection and Indication, Compliant with USB Battery Charging Specification, Rev 1.1
  - Supports Data Contact Detect (DCD)
- Negative-Swing-Capable Audio Channel
- Built-in Termination Resistors for Audio Pop Reduction
- Simple Switch Control Using Three Select Pins
- 28 V Over-Voltage Tolerance on V<sub>BUS</sub>

# **Applications**

Cell Phones, MP3 Players, PDAs

## **Description**

The FSA801 is a 3:1 USB accessory switch that enables USB data, stereo and mono audio, microphone, and UART data to share a common connector port. Two ports are designed for high-speed USB 2.0 signaling, while also capable of full-speed USB and UART communication. The architecture allows audio signals to swing below ground so a common USB and headphone jack can be used for personal media players and portable peripheral devices.

FSA801 detects wall chargers through a dedicated pin that provides the baseband with charger detection. The charger function is compliant with USB Battery Charging Specification, Rev 1.1, implementing Data Contact Detect (DCD) before detecting a charger. The FSA801 indicates if a Dedicated Charging Port (DCP) or a Charging Downstream Port (CDP) has been connected.

The FSA801 meets both USB Rev. 2.0 and micro-USB specifications.

# **Ordering Information**

Part Number	Operating Temperature Range	Top Mark	Package
FSA801UMX	-40 to +85°C	KL	16-Lead Quad, 1.8 x 2.6 mm Ultrathin Molded Leadless Package (UMLP)

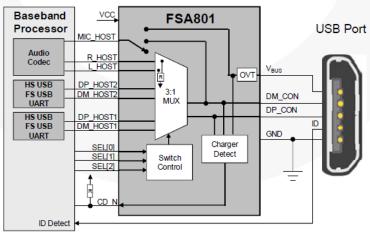


Figure 1. Typical Application

## **Functional Description**

The FSA801 USB2.0 accessory switch is designed to consolidate wired accessories for portable devices, such as cellular telephones and portable audio players. The benefits of consolidation include reduced space requirements from a reduction of connectors and their size. The micro-USB connector, for example, reduces connector height and depth, allowing for slimmer overall designs. Using the USB industry standard and a common connector type for accessories such as chargers and headsets, greatly reduces the waste associated with new phone purchases by allowing re-use of the accessories.

Using just five wires for all connection types considerably reduces the cost of wired accessories and simplifies their construction. The FSA801 facilitates adopting this methodology because it is designed to redirect the DP/DM pins from the USB connector to one of three ports at the baseband's discretion. Additional flexibility is provided by the ability of the microphone line to be switched from either the DP CON or VBUS pin.

The VBUS pin is protected up to 28 V without damage to the FSA801.

## **USB Charger Detection / Data Contact Detect**

The FSA801 senses the presence of USB chargers per the USB Battery Charging Specification, Version 1.1. This specification uses  $V_{BUS}$  status and measurements on DP\_CON / DM\_CON pins to determine that a charging device might be attached. The 'CD\_N' pin goes to a low state, indicating the presence of a charger. The charger-detect algorithm executes when  $V_{BUS}$  is valid. The charger-detection algorithm detects both Dedicated Charging Ports (DCP) and Charging Downstream Ports (CDP).

In this implementation, per the *USB Battery Charging Specification, Version 1.1*, the FSA801 implements Data Contact Detect (DCD) to insure the D+ and D- pins have made contact before the dedicated charger detection is performed.

Since the BC1.1 charger detection algorithm applies and detects signals on the D+ and D- lines, any additional loading effects from portable device host side of the switch would cause the results to be invalid. To prevent interference due to any loading, the FSA801 only performs charger detection when all switches are open.

Additionally, if all switches are open and  $V_{BUS}$  is present, the FSA801 does not close any switch path until the DCD circuitry detects contact with the D+/D- pins and the charger detection is complete. If the D+/D- pins never contact, but  $V_{BUS}$  is present, the USB switches cannot be closed when configuring from SEL[2:0]='000' to SEL[2:0]='001' or SEL[2:0]='010'. To override this blocking, first switch to a non-USB mode (one of the audio modes, SEL[2:0]='011','100' or '101'), and then to the desired USB mode.

If the USB physical layer device that the FSA801 is connected to also performs DCD, it should not start until after the FSA801 has time to finish its detection function (since the delay between VBUS connection and D+/D-connection is not defined, this detection function time cannot be defined either).

Glitches on VBUS that occur when  $V_{\text{BUS}}$  is not driven (positive voltage spikes and on-off situations at the beginning of a cable attach) are automatically filtered by the DCD state machine timing.

To manually reset the FSA801 to search for a charger again, switch to SEL[2:0]='111' for a minimum of 30  $\mu$ s. After this state machine is reset, the next time that SEL[2:0]='000' (all switches open) for a minimum of 30  $\mu$ s, the FSA801 begins the charger detection sequence.

**PLEASE NOTE**: The FSA801 is guaranteed to operate down to 2.4 V. If the FSA801  $V_{\rm CC}$  is connected directly to a battery and falls below 2.4 V, the FSA801 may not correctly detect a charger. If a charger is applied, the  $V_{\rm CC}$  should start to rise above 2.4 V. In this situation, the FSA801 does not automatically check for a charger again, so the FSA801 should be placed in SEL[2:0]='111' for 30  $\mu$ s (min.), then SEL[2:0]='000' for 30  $\mu$ s (min.) to perform the charger detection again.

## **Applications with Multiple USB Controllers**

When operating with two USB controllers, it is recommended to configure the switches to OPEN before switching to the other (second) USB interface. The OPEN setting duration should be long enough for the accessory to go to a SE0 state, so when the switch is set to the other (second) USB port, the new controller re-enumerates.

## **Mode Descriptions**

The FSA801 has three select pins to control the switching operations, SEL[0], SEL[1], and SEL[2] described in Table 1.

Table 1. Selection Truth Table

SEL[2]	SEL[1]	SEL[0]	Switch Action	Description
0	0	0	OPEN	Open all switch paths (device in low-power mode)
0	0	1	USB1, UART	Closes USB1 path to D+/D-, default condition <sup>(1)</sup> - DP_CON connected to DP_HOST1 - DM_CON connected to DM_HOST1
0	1	0	USB2, UART	Closes USB2 path to D+/D DP_CON connected to DP_HOST2 - DM_CON connected to DM_HOST2
0	1	1	AUDIO	Closes audio path to D+/D- only, no microphone switched - DP_CON connected to R_HOST - DM_CON connected to L_HOST
1	0	0	MONO AUDIO with MIC on D+ <sup>(2)</sup>	Closes audio path to DM_CON and microphone on DP_CON pin. This is a mono-audio application.  - DP_CON connected to MIC  - DM_CON connected to L_HOST
1	0	1	STEREO AUDIO with MIC on VBUS <sup>(2)</sup>	Closes audio path to D+/D- and microphone on V <sub>BUS</sub> pin. This mode is typically used for stereo headset with microphone.  - DP_CON connected to R_HOST  - DM_CON connected to L_HOST  - V <sub>BUS</sub> connected to MIC
1	1	0	Undefined	Reserved; do not use.
1	1	1	Charger Detection Reset	Charger Detection Reset. Selecting this mode for greater than 30 $\mu$ s resets the FSA801 to check for a charger, the next time a SEL[2:0] state of '000' is applied for more than 30 $\mu$ s.

#### Notes:

- 1. The SELECT pins are CMOS inputs and should not be left in a floating condition. Some applications require the UART path be in the CLOSED position on power-up for initial programming of the device under test. If that condition is desired, the three SELECT pins should be pulled to the correct levels with external resistors that should exceed 100 KΩ to reduce the static power consumption. In other applications, adding weak pull-down resistors to GND defaults the device to all paths open (low-power mode).
- 2. When the audio switch is in the OPEN position, the R and L are terminated to GND with internal termination resistors to discharge any stray capacitance that could cause audio pop.

# **Pin Configuration**

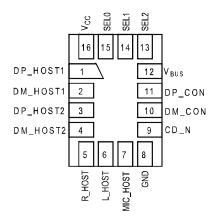


Figure 2. 16-Pin, UMLP Pin Assignments (Top-Through View)

# **Pin Descriptions**

Name	Pin#	Description					
USB, UART	Interface						
DP_HOST1	1	signal, dedicated USB port to be connected to the resident USB or UART transceiver on ephone.					
DM_HOST1	2	D- signal, dedicated USB port to be connected to the resident USB or UART transceiver on the phone.					
DP_HOST2	3	D+ signal, dedicated USB port to be connected to the resident USB or UART transceiver on the phone.					
DM_HOST2	4	O- signal, dedicated USB port to be connected to the resident USB or UART transceiver on the phone.					
Audio Interfa	ace						
R_HOST	5	Right audio channel from phone audio codec.					
L_HOST	6	Left audio channel from phone audio codec.					
MIC_HOST	7	Connected to the phone audio codec MIC input pin.					
Power Interf	ace						
V <sub>cc</sub>	16	Input voltage supply pin to be connected to the phone battery output.					
Connector In	nterface						
$V_{BUS}$	12	Input voltage supply pin to be connected to the V <sub>BUS</sub> pin of the USB connector.					
GND	8	Ground.					
DP_CON	11	Connected to the USB connector D+ pin; depending on the FSA801 signaling mode, this pin can share DP_HOST1, DP_HOST2 or R_HOST signals.					
DM_CON	10	Connected to the USB connector D- pin; depending on the FSA801 signaling mode, this pin can share DM_HOST1, DM_HOST2 or L_HOST signals.					
Charger Det	ection						
CD_N	9	Active-LOW, open-drain output pin; requires pull-up resistor to baseband I/O voltage supply					
Switch Cont	rol						
SEL[2:0]	13-15	Switch selection pins; refer to Table 1 for truth table.					

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Param		Min.	Max.	Unit		
V <sub>CC</sub>	Supply Voltage from Battery / Baseba	-0.5	6.0	V			
$V_{BUS}$	Voltage from Mini/Micro-USB Connec	ctor		-0.5	28.0	V	
		USB/UART Path Activ	е	-0.5	V <sub>BUS</sub> +0.5		
$V_{SW}$	Switch I/O Voltage	Stereo/Mono Audio Pa	ath Active	V <sub>CC</sub> -8.5	V <sub>CC</sub> +0.5	V	
		All Other Channels		-0.5	V <sub>CC</sub> +0.5		
I <sub>IK</sub>	Input Clamp Diode Current			-50		mA	
		USB			50		
$I_{SW}$	Switch I/O Current (Continuous)	Audio		60	mA		
		All Other Channels		50			
		USB		150	mA		
I <sub>SWPEAK</sub>	Peak Switch Current (Pulsed at 1ms Duration, <10% Duty Cycle)	Audio		150	mA		
	Buration, <10% Buty Cycle)	All Other Channels		150	mA		
T <sub>STG</sub>	Storage Temperature Range			-65	+150	°C	
$T_J$	Maximum Junction Temperature			+150	°C		
$T_L$	Lead Temperature (Soldering, 10 Sec		+260	°C			
		USB Connector Pins	Air Gap		15		
E00	IEC 61000-4-2 System	(D+, D-, V <sub>BUS</sub> )	Contact		8		
ESD	Human Body Model, JEDEC JESD22-A114 All Pins				3	kV	
	Charged Device Model, JEDEC JESE	)22-C101	All Pins		2		

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter			Max.	Units
V <sub>CC</sub>	Battery Supply Voltage		2.7	4.4	V
		USB/UART Path Active	0	4.4	V
$V_{SW}$	Switch I/O Voltage	Audio Path Active	V <sub>CC</sub> -7.0	2.0	V
		Mic Path Active	0	V <sub>CC</sub> -1	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C

## **Switch Path DC Electrical Characteristics**

All typical values are at 25°C unless otherwise specified.

Cumbal	Doromotor	V (A)	Conditions	$T_A = -40 \text{ to } +85^\circ$		-85°C	Unit
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min.	Тур.	Max.	Onit
Host Interfa	ace Pins (SEL[2:0])						
V <sub>IH</sub>	Input High Voltage	3.2 to 4.4		1.3			V
V <sub>IL</sub>	Input Low Voltage	3.2 to 4.4				0.7	V
I <sub>IN</sub>	Control Input Leakage	0 to 4.4	V <sub>SW</sub> =0 to V <sub>CC</sub>	-1		1	μΑ
l <sub>oz</sub>	Off State Leakage	4.4	0 ≤ DP_CON, DM_CON, DP_HOSTn, DM_HOSTn, R_HOST, L_HOST ≤ 3.6 V	-2		2	μA
Charger De	etect Pin (CD_N)						
$V_{OL}$	Output Low Voltage	3.2 to 4.4	I <sub>OL</sub> =10 mA			0.4	V
V <sub>BUS</sub> Pin							
V <sub>BUSTH</sub>	Charger Detect Threshold	3.2 to 4.4			3.3		V
I <sub>BUSIN</sub>	V <sub>BUS</sub> Input Leakage	0 to 4.4			2	10	μA
Switch Off	Characteristics						1
l <sub>OFF</sub>	Power Off Leakage Current	0	All Ports Except MIC & Audio Path V <sub>SW</sub> =0 V to 4.4 V, Figure 7			10	μA
USB Switcl	h On Paths						
R <sub>ONUSB</sub>	HS USB Range Switch On Resistance	3.2 to 4.4	V <sub>DP_CON/DM_CON</sub> =0 V, 0.4 V, I <sub>ON</sub> =8 mA, Figure 6		6	9	Ω
R <sub>ONUART</sub>	UART Range Switch On Resistance	3.2 to 4.4	V <sub>DP_CON/DM_CON</sub> =0 V, 3.2 V, I <sub>ON</sub> =8 mA, Figure 6		8		Ω
Audio R/L	Switch On Paths				•		
R <sub>ONAUD</sub>	Audio Switch On Resistance	3.2 to 4.4	V <sub>L/R</sub> =-0.8 V, 0.8 V, I <sub>ON</sub> =30 mA,			3	Ω
R <sub>FLAT</sub>	Audio R <sub>ON</sub> Flatness <sup>(3)</sup>	3.8	Figure 6		0.16		Ω
R <sub>TERM</sub>	Internal Termination Resistors				1		kΩ
MIC Switch	On Path				•		
В	Switch On Resistance	3.2 to 4.4	SEL[2:0]=100 (MIC to DP_CON), V <sub>SW</sub> =0 V, 1.6 V, I <sub>ON</sub> =8 mA, Figure 6		15		Ω
R <sub>ONMIC</sub>	Switch Off Resistance	3.2 10 4.4	SEL[2:0]=101 (MIC to VBUS), $V_{SW}$ =0 V, 1.6 V, $I_{ON}$ =8 mA, Figure 6		28		Ω
Total Switc	ch Current Consumption						
I <sub>CCSL</sub>	Battery Supply Sleep Mode Average Current	3.2 to 4.4	Static Current During Sleep Mode (SEL[2:0]=0)			1	μA
І <sub>ссwк</sub>			USB/UART Mode		20	35	μA
	Battery Supply Active Mode Average Current	3.2 to 4.4	Audio Mode (SEL[2:0]=011), V <sub>BUS</sub> =0 V			1	μΑ
			Audio Mode (SEL[2:0]=100, 101)		20	35	μA
l:-	Increase in I <sub>CCSL</sub> /I <sub>CCWK</sub> Current	3.2 to 4.4	$V_{SEL}$ = 2.8 V and $V_{CC}$ = 4.4 V			8	μA
ICCSELT	per Control Voltage and V <sub>CC</sub>	3.2 10 4.4	V <sub>SEL</sub> = 1.8 V and V <sub>CC</sub> = 4.4 V			10	μΑ

## Note:

3. Flatness is defined as the difference between the maximum and minimum values of on resistance over the specified range of conditions.

# Switch Path AC Electrical Characteristics<sup>(4)</sup>

All typical value are for  $V_{\text{CC}}$  =3.8 V at 25°C unless otherwise specified.

Symbol	Parameter		V <sub>cc</sub>	Conditions	$T_A = -40 \text{ to } +85^{\circ}\text{C}$			Unit	Figure
Symbol	Г	arameter .	(V)	Conditions	Min.	Тур.	Max.	Oilie	rigure
	Active Channel	Audio Mode	3.8	f=20 kHz, $R_T$ =32 $\Omega$ , $C_L$ =0 pF		-95			
	Crosstalk DP_CON to DM_CON	USB Mode	3.8	f=1 MHz, $R_T$ =50 $\Omega$ , $C_L$ =0 pF		-78			
Xtalk		USB Wode	3.0	f=240 MHz, $R_T$ =50 $\Omega$ , $C_L$ =0 pF		-36		dB	Figure 9
	Active Channel	MIC on VBUS to R_HOST, L_HOST	3.8	f=20 kHz, $R_T$ =32 $\Omega$ , $C_L$ =0 pF		-93			
	Crosstalk MIC	MIC on DP_CON to L_HOST	3.8	f=20 kHz, $R_T$ =32 $\Omega$ , $C_L$ =0 pF		-105			
		Audio Rejection L_HOST to DM_CON, R_HOST to DP_CON	3.8	f=20 kHz, $R_T$ =32 $\Omega$ , $C_L$ =0 pF		-100		dB	
		MIC Rejection MIC_HOST to DP_CON	3.8	f=20 kHz, $R_T$ =50 $\Omega$ , $C_L$ =0pF		-110			
O <sub>IRR</sub>	Off Isolation	MIC Rejection MIC_HOST to VBUS	3.8	f=20 kHz, $R_T$ =50 $\Omega$ , $C_L$ =0 pF		-110			Figure 8
	Rejection Ratio	USB Rejection	3.8	f=1 MHz, $R_T$ =50 $\Omega$ , $C_L$ =0 pF		-85			
				f=240 MHz, $R_T$ =50 Ω, $C_L$ =0 pF		-35			
PSRR	Power Supply Rejection Ratio MIC on VBUS or MIC on DP_CON, to VCC or GND		3.8	Power Supply Noise 300Mv <sub>PP</sub> , f=217Hz		-110		dB	
THD+N	Total Harmonic [	Distortion + Noise 3.8	20 Hz to 20 kHz, R <sub>L</sub> =16 Ω, Input Signal Range 1.6 V <sub>PP</sub>		0.10		%	Figure 13	
וויטלוו	(Audio Path)			20 Hz to 20 kHz, R <sub>L</sub> =32 Ω, Input Signal Range 1.6 V <sub>PP</sub>		0.07		%	Figure 13
t <sub>CDR</sub>	Charger Detection Reset Time: Minimum time in Selected State to Reset Charger Detection State Machine.		3.8	SEL[2:0]='111'	30			μs	
t <sub>CDL</sub>		on Start Time: Minimum State to Start Charger nce	3.8	SEL[2:0]='000'	30			μs	

## Note:

# Capacitance

Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	T <sub>A</sub> = -40 to +85°C		Unit	Figure
Syllibol	Farameter	V <sub>CC</sub> (V)	Conditions	Тур.	Max.	Onn	rigure
C <sub>IN</sub>	Select Pins Capacitance <sup>(5)</sup>	0	V <sub>BIAS</sub> =0.2 V	2.5		pF	Figure 11
C <sub>OFF(D+, D-)</sub>	D+, D- On Capacitance (HS USB Mode) <sup>(5)</sup>	3.8	V <sub>BIAS</sub> =0.2 V, f=1 MHz	4.7		pF	Figure 11
C <sub>ON(D+, D-)</sub>	D+, D- On Capacitance (HS USB Mode) <sup>(5)</sup>	3.8	V <sub>BIAS</sub> =0.2 V, f=1 MHz	7.6		pF	Figure 12

#### Note:

<sup>4.</sup> Guaranteed by characterization, not production tested.

<sup>5.</sup> Guaranteed by characterization, not production tested.

# **High-Speed USB Eye Compliance Results**

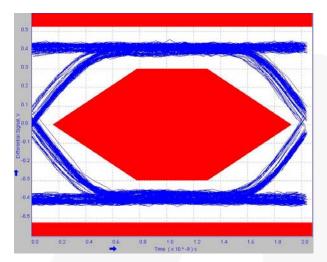


Figure 3. High-Speed Test Results (DP\_CON/DM\_CON - DP\_HOST1/DM\_HOST1)

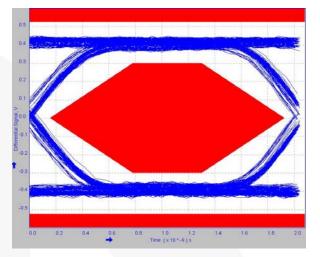


Figure 4. High-Speed Test Results (DP\_CON/DM\_CON - DP\_HOST2/DM\_HOST2)

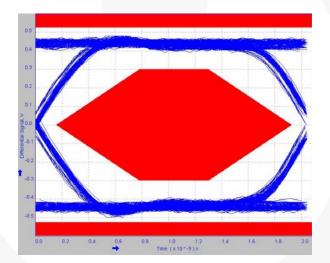


Figure 5. High-Speed Eye Compliance Input Signal

# **Test Diagrams**

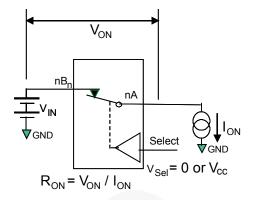
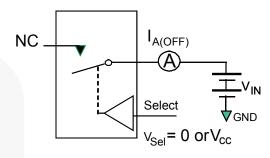


Figure 6. On Resistance



\*\*Each switch port is tested separately.

Figure 7. Off Leakage

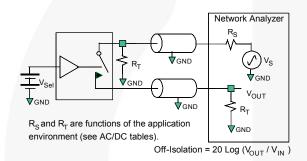


Figure 8. Channel Off Isolation

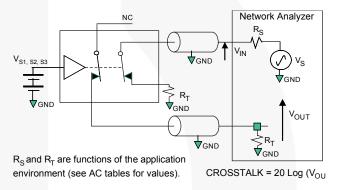


Figure 9. Active Channel Crosstalk

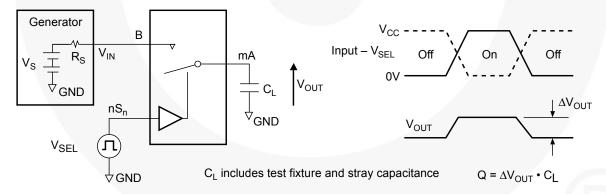


Figure 10. Charge Injection Test

# Test Diagrams (Continued)

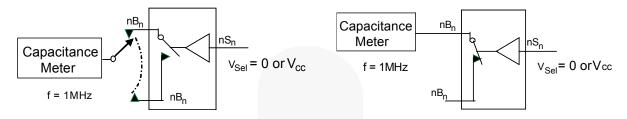


Figure 11. Channel Off Capacitance

Figure 12. Channel On Capacitance

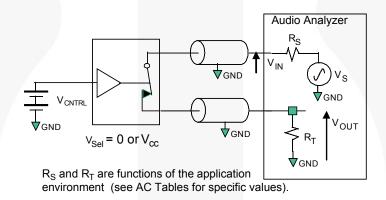
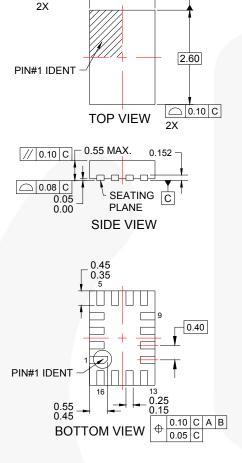


Figure 13. Total Harmonic Distortion + Noise

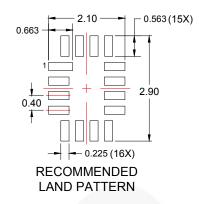
# **Physical Dimensions**

○ 0.10 C

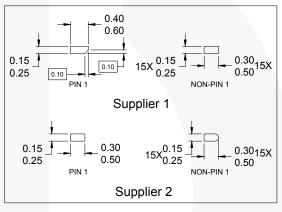


1.80

-AB

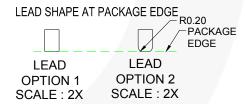


## TERMINAL SHAPE VARIANTS



## NOTES:

- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY.
- E. DRAWING FILENAME: MKT-UMLP16Arev4.
- F. TERMINAL SHAPE MAY VARY ACCORDING TO PACKAGE SUPPLIER, SEE TERMINAL SHAPE VARIANTS.



### Figure 14. 16-Lead, Ultrathin Molded Leadless Package (UMLP)

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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